

Features

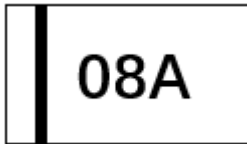
- Stand-off voltage: 8V Max
- Transient protection for each line according to
IEC61000-4-2(ESD): $\pm 8\text{kV}$ (contact)
IEC61000-4-5(surge): 26A (8/20 μs)
- Low leakage current
- Low clamping voltage: $V_{\text{CL}} = 17\text{V}$ max. @ IPP = 26A (TLP)
- RoHS Compliant
- Compliant to Halogen-free

Applications

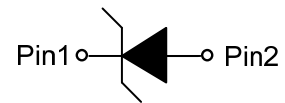
- Power supply protection
- Power management

Mechanical Data

- Package: DFN-2L
- Case Material: "Green" Molding Compound
- Marking Information: See Below



0402(DFN-2L)



PIN Configuration

Maximum Ratings

PARAMETER	SYMBOL	LIMITS	UNIT
Peak pulse power ($t_p = 8/20\mu\text{s}$)	P_{pk}	422	W
Peak pulse current ($t_p = 8/20\mu\text{s}$)	I_{PP}	26	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	± 30	KV
ESD according to IEC61000-4-2 contact discharge		± 8	
Junction temperature	T_J	125	$^{\circ}\text{C}$
Storage temperature	T_{STG}	-55~150	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ Unless otherwise specified)

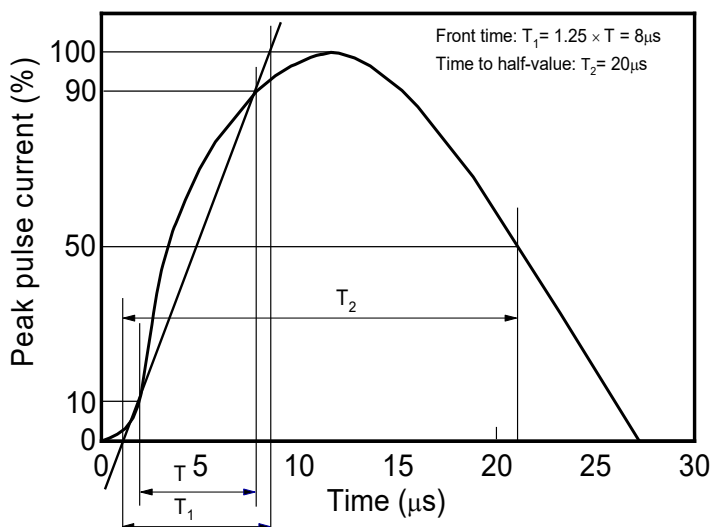
PARAMETER	Symbol	UNIT	Conditions	Min	Typ	Max
Reverse maximum working voltage	V_{RWM}	V				8
Reverse leakage current	I_R	μA	$V_{RWM} = 8\text{V}$,			1
Reverse breakdown voltage	$V_{(BR)}$	V	$I_T = 1\text{mA}$,	8		10
Clamping voltage	V_{CL}	V	$I_{PP} = 1\text{A}$, $t_p = 8/20\mu\text{s}$			13
		V	$I_{PP} = 26\text{A}$, $t_p = 8/20\mu\text{s}$			17
Junction capacitance	CJ	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$		195	

Notes:

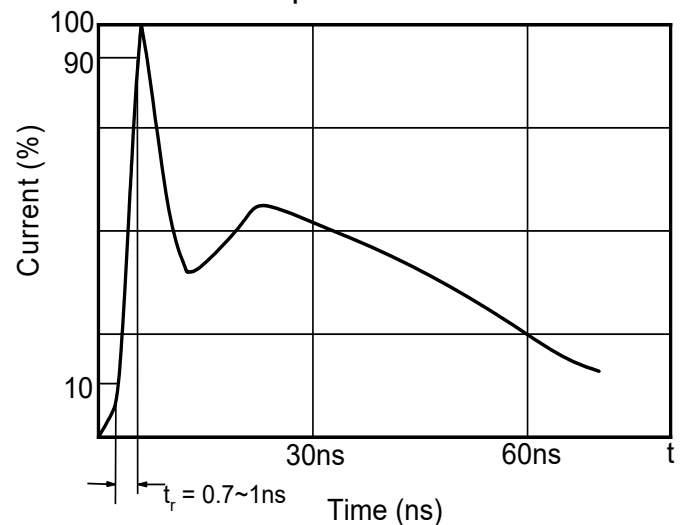
- (1). TLP parameter: $Z_0 = 50\Omega$, $t_p = 100\text{ns}$, $t_r = 2\text{ns}$, averaging window from 60ns to 80ns. RDYN is calculated from 4A to 16A.
- (2). Contact discharge mode, according to IEC61000-4-2.
- (3). Non-repetitive current pulse, according to IEC61000-4-5.

Characteristics (Typical)

8/20 μs waveform per IEC61000-4-5

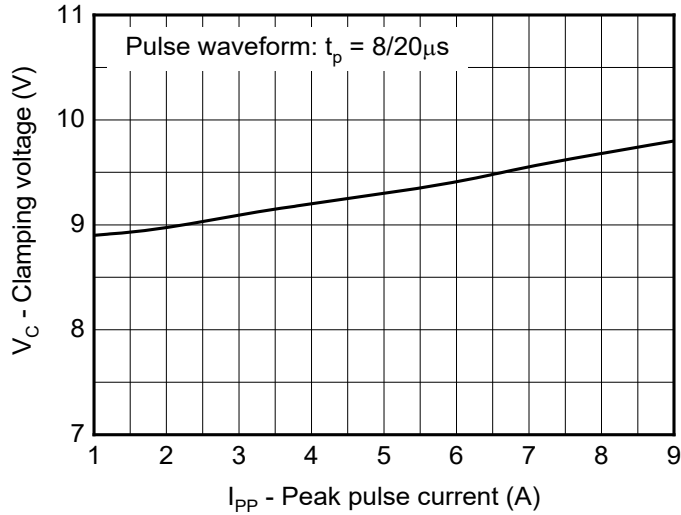


Contact discharge current waveform per IEC61000-4-2

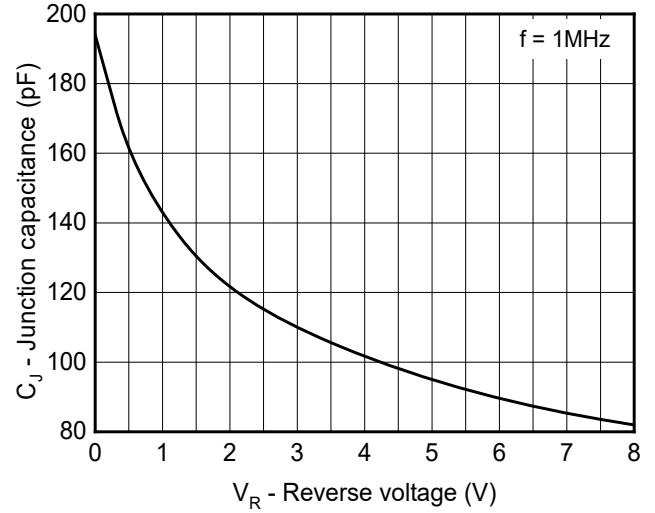


Characteristics (Typical)

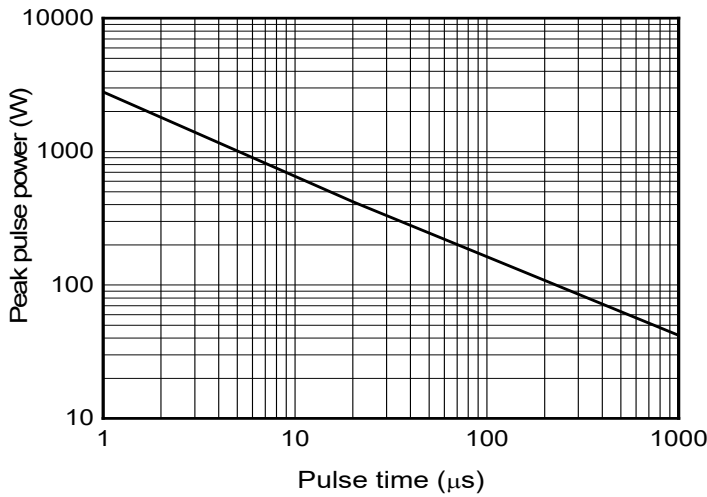
Clamping voltage vs. Peak pulse current



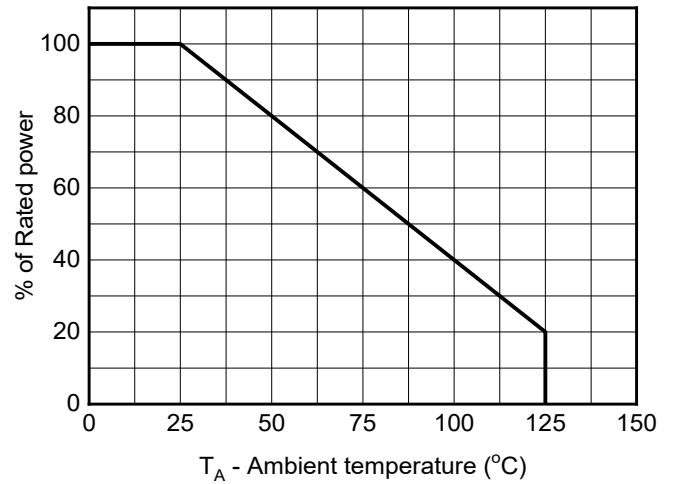
Capacitance vs. Reverse voltage



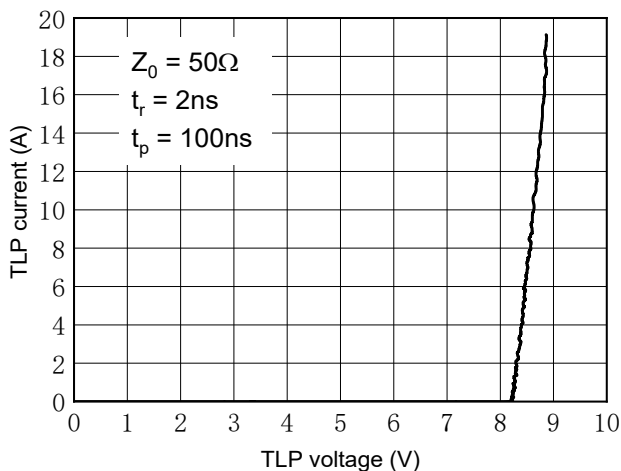
Non-repetitive peak pulse power vs. Pulse time



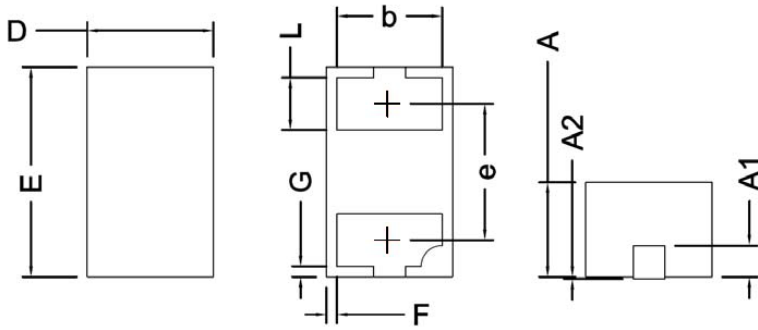
Power derating vs. Ambient temperature



TLP Measurement

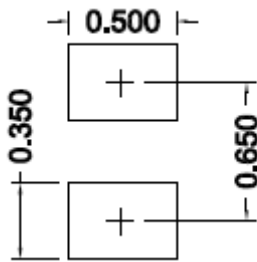


Outline Dimensions



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	0.50	0.60	0.70
E	0.90	1.00	1.10
A	0.35	0.45	0.55
A1	0.15 BSC		
A2			0.10
F	0.005		
G	0.005		
L	0.15	0.25	0.35
b	0.41	0.50	0.59
e	0.65 BSC		

Recommended PCB Layout



Unit:mm

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met